

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B**
JFET-INPUT OPERATIONAL AMPLIFIERS
SLOS081G – FEBRUARY 1977 – REVISED SEPTEMBER 2004

- Low Power Consumption
- Wide Common-Mode and Differential Voltage Ranges
- Low Input Bias and Offset Currents
- Output Short-Circuit Protection
- Low Total Harmonic Distortion . . . 0.003% Typ
- High Input Impedance . . . JFET-Input Stage
- Latch-Up-Free Operation
- High Slew Rate . . . 13 V/ μ s Typ
- Common-Mode Input Voltage Range Includes V_{CC+}

description/ordering information

The TL08x JFET-input operational amplifier family is designed to offer a wider selection than any previously developed operational amplifier family. Each of these JFET-input operational amplifiers incorporates well-matched, high-voltage JFET and bipolar transistors in a monolithic integrated circuit. The devices feature high slew rates, low input bias and offset currents, and low offset-voltage temperature coefficient. Offset adjustment and external compensation options are available within the TL08x family.

The C-suffix devices are characterized for operation from 0°C to 70°C. The I-suffix devices are characterized for operation from -40°C to 85°C. The Q-suffix devices are characterized for operation from -40°C to 125°C. The M-suffix devices are characterized for operation over the full military temperature range of -55°C to 125°C.

ORDERING INFORMATION

T _J	V _{I0max} AT 25°C	PACKAGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	15 mV	PDIP (P)	Tube of 50	TL081CP
			Tube of 50	TL082CP
		PDIP (N)	Tube of 25	TL084CN
		SOIC (D)	Tube of 75	TL081CD
			Reel of 2500	TL081CDR
			Tube of 75	TL082CD
			Reel of 2500	TL082CDR
			Tube of 50	TL084CD
			Reel of 2500	TL084CDR
		SOP (PS)	Reel of 2000	TL081CPSR
			Reel of 2000	TL082CPSR
		SOP (NS)	Reel of 2000	TL084CNSR
		TSSOP (PW)	Tube of 150	TL082CPW
			Reel of 2000	TL082CPWR
			Tube of 90	TL084CPW
			Reel of 2000	TL084CPWR

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

TL081, TL081A, TL081B, TL082, TL082A, TL082B**TL084, TL084A, TL084B****JFET-INPUT OPERATIONAL AMPLIFIERS**

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description/ordering information (continued)**ORDERING INFORMATION**

T _J	V _{IOMAX} AT 25°C	PACKAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	6 mV	PDIP (P)	Tube of 50	TL081ACP
			Tube of 50	TL082ACP
		PDIP (N)	Tube of 25	TL084ACN
		SOIC (D)	Tube of 75	TL081ACD
			Reel of 2500	TL081ACDR
			Tube of 75	TL082ACD
			Reel of 2500	TL082ACDR
			Tube of 50	TL084ACD
			Reel of 2500	TL084ACDR
		SOP (PS)	Reel of 2000	TL082ACPSR
		SOP (NS)	Reel of 2000	TL084ACNSR
	3 mV	PDIP (P)	Tube of 50	TL081BCP
			Tube of 50	TL082BCP
		PDIP (N)	Tube of 25	TL084BCN
		SOIC (D)	Tube of 75	TL081BCD
			Reel of 2500	TL081BCDR
			Tube of 75	TL082BCD
			Reel of 2500	TL082BCDR
			Tube of 50	TL084BCD
			Reel of 2500	TL084BCDR
-40°C to 85°C	6 mV	PDIP (P)	Tube of 50	TL081IP
			Tube of 50	TL082IP
		PDIP (N)	Tube of 25	TL084IN
		SOIC (D)	Tube of 75	TL081ID
			Reel of 2500	TL081IDR
			Tube of 75	TL082ID
			Reel of 2500	TL082IDR
			Tube of 50	TL084ID
			Reel of 2500	TL084IDR
		TSSOP (PW)	Reel of 2000	TL082IPWR
-40°C to 125°C	9 mV	SOIC (D)	Tube of 50	TL084QD
			Reel of 2500	TL084QDR
-55°C to 125°C	9 mV	CDIP (J)	Tube of 25	TL084MJ
		LCCC (FK)	Reel of 55	TL084FK
	6 mV	CDIP (JG)	Tube of 50	TL082MJJ
		LCCC (FK)	Tube of 55	TL082MFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

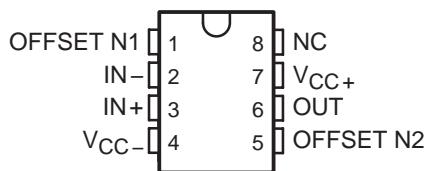
TL081, TL081A, TL081B, TL082, TL082A, TL082B

TL084, TL084A, TL084B

JFET-INPUT OPERATIONAL AMPLIFIERS

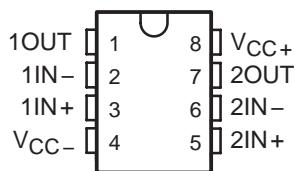
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**TL081, TL081A, TL081B
D, P, OR PS PACKAGE
(TOP VIEW)**

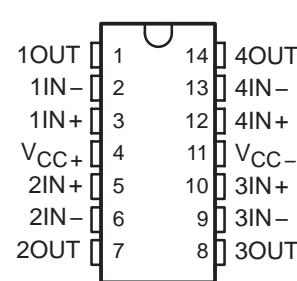


NC – No internal connection

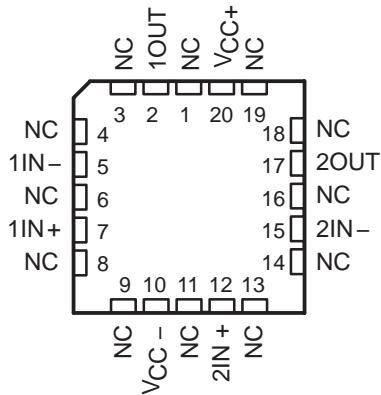
**TL082, TL082A, TL082B
D, JG, P, PS, OR PW PACKAGE
(TOP VIEW)**



**TL084, TL084A, TL084B
D, J, N, NS, OR PW PACKAGE
(TOP VIEW)**

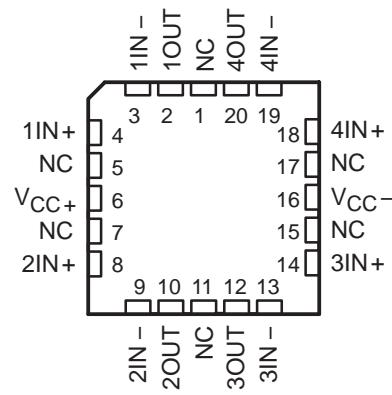


**TL082M . . . FK PACKAGE
(TOP VIEW)**



NC – No internal connection

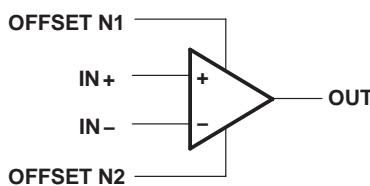
**TL084M . . . FK PACKAGE
(TOP VIEW)**



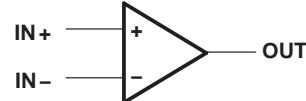
NC – No internal connection

symbols

TL081



**TL082 (EACH AMPLIFIER)
TL084 (EACH AMPLIFIER)**



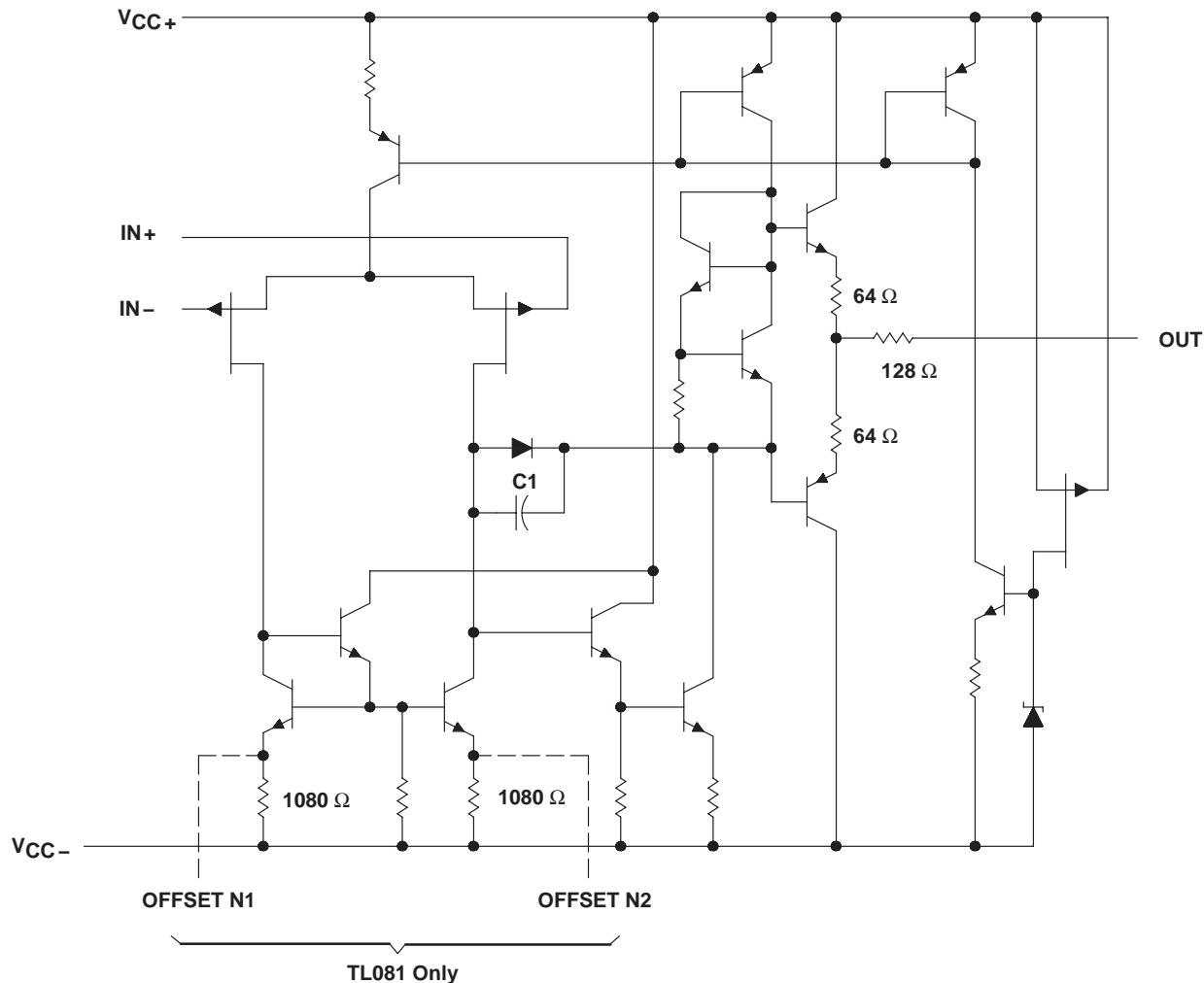
TL081, TL081A, TL081B, TL082, TL082A, TL082B

TL084, TL084A, TL084B

JFET-INPUT OPERATIONAL AMPLIFIERS

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schematic (each amplifier)



Component values shown are nominal.

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B
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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

	TL08_C TL08_AC TL08_BC	TL08_I	TL084Q	TL08_M	UNIT
Supply voltage, V _{CC+} (see Note 1)	18	18	18	18	V
Supply voltage V _{CC-} (see Note 1)	-18	-18	-18	-18	V
Differential input voltage, V _{ID} (see Note 2)	±30	±30	±30	±30	V
Input voltage, V _I (see Notes 1 and 3)	±15	±15	±15	±15	V
Duration of output short circuit (see Note 4)	Unlimited	Unlimited	Unlimited	Unlimited	
Continuous total power dissipation		See Dissipation Rating Table			
Operating free-air temperature range, T _A	0 to 70	-40 to 85	-40 to 125	-55 to 125	°C
Package thermal impedance, θ _{JA} (see Notes 5 and 6)	D package (8-pin)	97	97		°C/W
	D package (14-pin)	86	86		
	N package (14-pin)	76	76		
	NS package (14-pin)	80			
	P package (8-pin)	85	85		
	PS package (8-pin)	95	95		
	PW package (8-pin)	149			
	PW package (14-pin)	113	113		
Operating virtual junction temperature	150	150	150	150	°C
Case temperature for 60 seconds, T _C	FK package			260	°C
Lead temperature 1.6 mm (1/16 inch) from case for 60 seconds	J or JG package			300	°C
Storage temperature range, T _{stg}	-65 to 150	-65 to 150	-65 to 150	-65 to 150	°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}.
 2. Differential voltages are at IN+ with respect to IN-.
 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 4. The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
 5. Maximum power dissipation is a function of T_{J(max)}, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_{J(max)} - T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
 6. The package thermal impedance is calculated in accordance with JESD 51-7.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR	DERATE ABOVE T _A	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
D (14 pin)	680 mW	7.6 mW/°C	60°C	604 mW	490 mW	186 mW
FK	680 mW	11.0 mW/°C	88°C	680 mW	680 mW	273 mW
J	680 mW	11.0 mW/°C	88°C	680 mW	680 mW	273 mW
JG	680 mW	8.4 mW/°C	69°C	672 mW	546 mW	210 mW

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B
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electrical characteristics, $V_{CC\pm} = \pm 15$ V (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T_A^\dagger	TL081C TL082C TL084C			TL081AC TL082AC TL084AC			TL081BC TL082BC TL084BC			TL081I TL082I TL084I			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_O = 0$ $R_S = 50 \Omega$	$25^\circ C$ Full range	3	15	20	3	6	7.5	2	3	5	3	6	9	mV
αV_{IO} Temperature coefficient of input offset voltage	$V_O = 0$ $R_S = 50 \Omega$	Full range	18			18			18			18			$\mu V/C$
I_{IO} Input offset current‡	$V_O = 0$	$25^\circ C$ Full range	5	200		5	100		5	100		5	100		pA
I_B Input bias current†	$V_O = 0$	$25^\circ C$ Full range	30	400		30	200		30	200		30	200		pA
V_{ICR} Common-mode input voltage range		$25^\circ C$	± 11	-12	± 11	± 11	-12	± 11	-12	± 11	-12	± 11	-12	± 11	nA
V_{OM} Maximum peak output voltage swing	$R_L = 10 k\Omega$ $R_L \geq 10 k\Omega$ $R_L \geq 2 k\Omega$	$25^\circ C$ Full range	± 12	± 13.5	± 12	± 12	± 13.5	± 12	± 13.5	± 12	± 13.5	± 12	± 13.5	± 12	V
A_{VD} Large-signal differential voltage amplification	$V_O = \pm 10 V, R_L \geq 2 k\Omega$ $V_O = \pm 10 V, R_L \geq 2 k\Omega$	$25^\circ C$ Full range	25	200		50	200		50	200		50	200		V/mV
B_1 Unity-gain bandwidth		$25^\circ C$	15			25			25			25			MHz
r_i Input resistance		$25^\circ C$				1012			1012			1012			Ω
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICR\min}, R_S = 50 \Omega$ $V_O = 0,$ $R_S = 50 \Omega$	$25^\circ C$	70	86	75	86	75	86	75	86	75	86	75	86	dB
$kSVR$ Supply-voltage rejection ratio ($\Delta V_{CC\pm} / \Delta V_{IO}$)	$V_{CC} = \pm 15 V \text{ to } \pm 9 V, R_S = 50 \Omega$ $V_O = 0,$ $R_S = 50 \Omega$	$25^\circ C$	70	86	80	86	80	86	80	86	80	86	80	86	dB
I_{CC} Supply current (per amplifier)	$V_O = 0,$ No load	$25^\circ C$	1.4	2.8		1.4	2.8		1.4	2.8		1.4	2.8		mA
V_{O1}/V_{O2} Crosstalk attenuation	$A_{VD} = 100$	$25^\circ C$	120			120			120			120			dB

† All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified. Full range for T_A is $0^\circ C$ to $70^\circ C$ for TL08_C, TL08_AC, TL08_BC and $-40^\circ C$ to $85^\circ C$ for TL08_I.

‡ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 17. Pulse techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B**
JFET-INPUT OPERATIONAL AMPLIFIERS
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electrical characteristics, $V_{CC} \pm = \pm 15$ V (unless otherwise noted)

PARAMETER	TEST CONDITIONS [†]	T_A	TL081M, TL082M			TL084Q, TL084M			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_O = 0, R_S = 50 \Omega$	25°C	3	6		3	9		mV
		Full range		9			15		
αV_{IO} Temperature coefficient of input offset voltage	$V_O = 0, R_S = 50 \Omega$	Full range		18			18		$\mu\text{V}/^\circ\text{C}$
I_{IO} Input offset current [‡]	$V_O = 0$	25°C	5	100		5	100		pA
		125°C		20			20		nA
I_{IB} Input bias current [‡]	$V_O = 0$	25°C	30	200		30	200		pA
		125°C		50			50		nA
V_{ICR} Common-mode input voltage range		25°C	–12 ±11 to 15			–12 ±11 to 15			V
V_{OM} Maximum peak output voltage swing	$R_L = 10 \text{ k}\Omega$	25°C	±12	±13.5		±12	±13.5		V
	$R_L \geq 10 \text{ k}\Omega$	Full range	±12			±12			
	$R_L \geq 2 \text{ k}\Omega$		±10	±12		±10	±12		
A_{VD} Large-signal differential voltage amplification	$V_O = \pm 10 \text{ V}, R_L \geq 2 \text{ k}\Omega$	25°C	25	200		25	200		V/mV
	$V_O = \pm 10 \text{ V}, R_L \geq 2 \text{ k}\Omega$	Full range	15			15			
B_1 Unity-gain bandwidth		25°C	3			3			MHz
r_i Input resistance		25°C		10^{12}			10^{12}		Ω
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICR\min}, V_O = 0, R_S = 50 \Omega$	25°C	80	86		80	86		dB
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC} \pm / \Delta V_{IO}$)	$V_{CC} = \pm 15 \text{ V to } \pm 9 \text{ V}, V_O = 0, R_S = 50 \Omega$	25°C	80	86		80	86		dB
I_{CC} Supply current (per amplifier)	$V_O = 0, \text{ No load}$	25°C	1.4	2.8		1.4	2.8		mA
V_{O1}/V_{O2} Crosstalk attenuation	$A_{VD} = 100$	25°C	120			120			dB

[†] All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.

[‡] Input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 17. Pulse techniques must be used that maintain the junction temperatures as close to the ambient temperature as possible.

operating characteristics, $V_{CC} \pm = \pm 15$ V, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
SR Slew rate at unity gain	$V_I = 10 \text{ V}, R_L = 2 \text{ k}\Omega, C_L = 100 \text{ pF}$, See Figure 1			8*	13		V/ μs
	$V_I = 10 \text{ V}, R_L = 2 \text{ k}\Omega, C_L = 100 \text{ pF}, T_A = -55^\circ\text{C to } 125^\circ\text{C}$, See Figure 1				5*		
t_r Rise time	$V_I = 20 \text{ mV}, R_L = 2 \text{ k}\Omega, C_L = 100 \text{ pF}$, See Figure 1			0.05			μs
				20			%
V_n Equivalent input noise voltage	$R_S = 20 \Omega$	$f = 1 \text{ kHz}$		18			$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10 \text{ Hz to } 10 \text{ kHz}$		4			μV
I_n Equivalent input noise current	$R_S = 20 \Omega$	$f = 1 \text{ kHz}$		0.01			$\text{pA}/\sqrt{\text{Hz}}$
THD Total harmonic distortion	$V_{Irms} = 6 \text{ V}, f = 1 \text{ kHz}$	$A_{VD} = 1, R_S \leq 1 \text{ k}\Omega, R_L \geq 2 \text{ k}\Omega$		0.003			%

*On products compliant to MIL-PRF-38535, this parameter is not production tested.

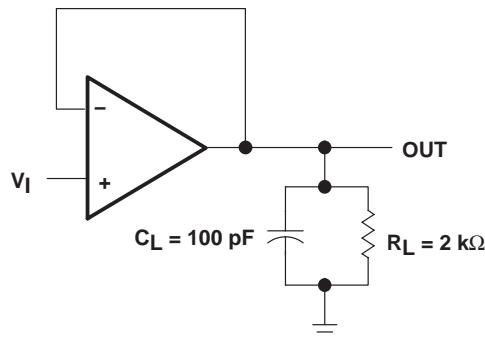
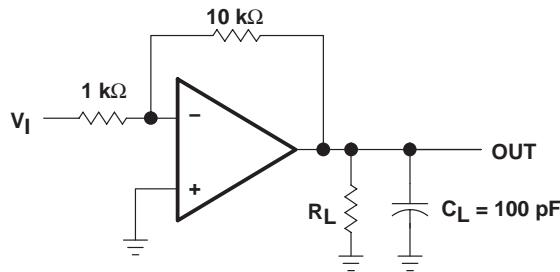
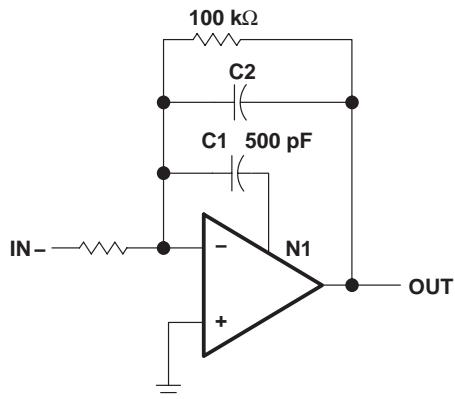
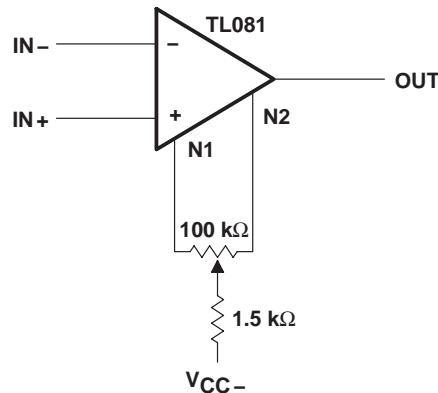


TL081, TL081A, TL081B, TL082, TL082A, TL082B**TL084, TL084A, TL084B****JFET-INPUT OPERATIONAL AMPLIFIERS**

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operating characteristics, $V_{CC\pm} = \pm 15$ V, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT	
SR Slew rate at unity gain	$V_I = 10$ V,	$R_L = 2$ k Ω ,	$C_L = 100$ pF,	See Figure 1	8	13		V/ μ s
t_r Rise time	$V_I = 20$ mV,	$R_L = 2$ k Ω ,	$C_L = 100$ pF,	See Figure 1	0.05			μ s
Overshoot factor					20			%
V_n Equivalent input noise voltage	$R_S = 20$ Ω	$f = 1$ kHz			18			nV/ $\sqrt{\text{Hz}}$
		$f = 10$ Hz to 10 kHz			4			μ V
I_n Equivalent input noise current	$R_S = 20$ Ω ,	$f = 1$ kHz			0.01			pA/ $\sqrt{\text{Hz}}$
THD Total harmonic distortion	$V_{I\text{rms}} = 6$ V, $f = 1$ kHz	$A_{VD} = 1$,	$R_S \leq 1$ k Ω ,	$R_L \geq 2$ k Ω ,	0.003			%

PARAMETER MEASUREMENT INFORMATION**Figure 1****Figure 2****Figure 3****Figure 4**

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B**
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TYPICAL CHARACTERISTICS

Table of Graphs

		FIGURE
V _{OM}	Maximum peak output voltage	vs Frequency 5, 6, 7 vs Free-air temperature 8 vs Load resistance 9 vs Supply voltage 10
AVD	Large-signal differential voltage amplification	vs Free-air temperature 11 vs Frequency 12
	Differential voltage amplification	vs Frequency with feed-forward compensation 13
P _D	Total power dissipation	vs Free-air temperature 14
I _{CC}	Supply current	vs Free-air temperature 15 vs Supply voltage 16
I _{IB}	Input bias current	vs Free-air temperature 17
	Large-signal pulse response	vs Time 18
V _O	Output voltage	vs Elapsed time 19
CMRR	Common-mode rejection ratio	vs Free-air temperature 20
V _n	Equivalent input noise voltage	vs Frequency 21
THD	Total harmonic distortion	vs Frequency 22

**MAXIMUM PEAK OUTPUT VOLTAGE
vs
FREQUENCY**

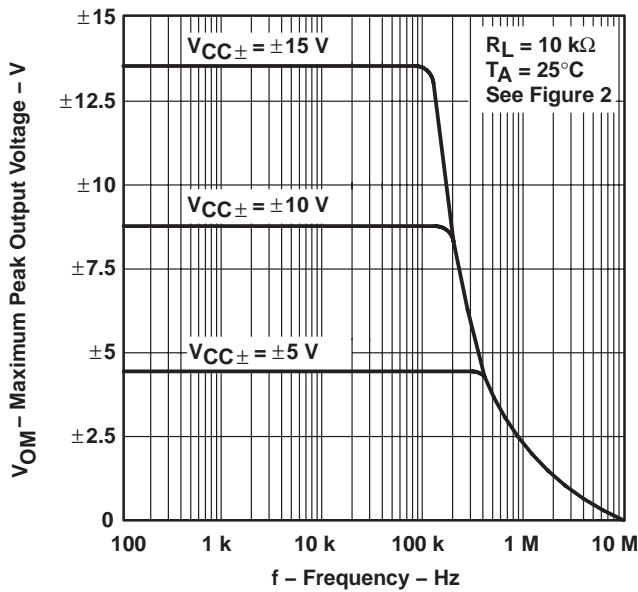


Figure 5

**MAXIMUM PEAK OUTPUT VOLTAGE
vs
FREQUENCY**

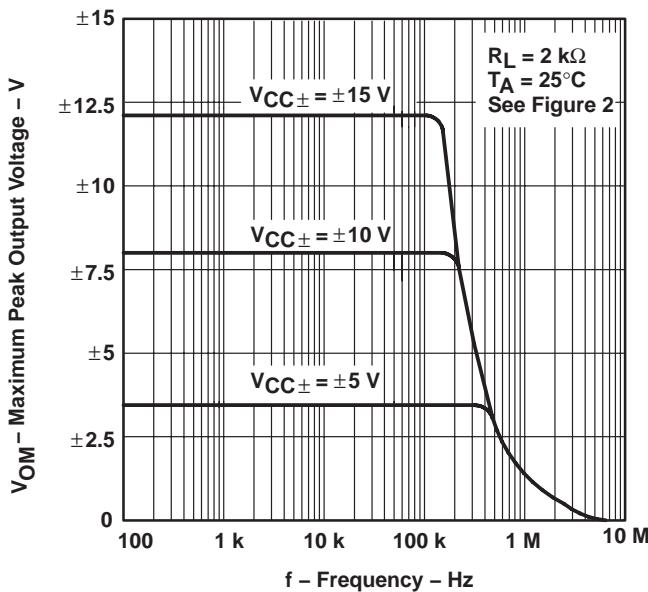


Figure 6

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
 TL084, TL084A, TL084B
 JFET-INPUT OPERATIONAL AMPLIFIERS**

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TYPICAL CHARACTERISTICS†

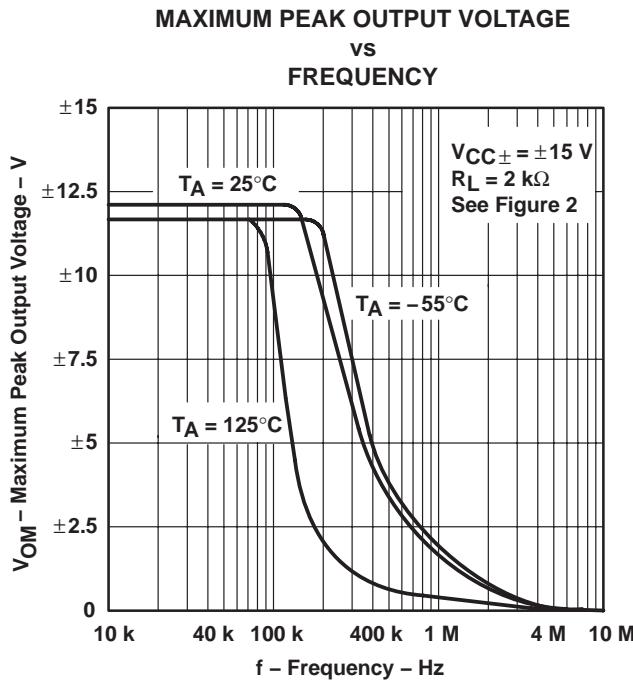


Figure 7

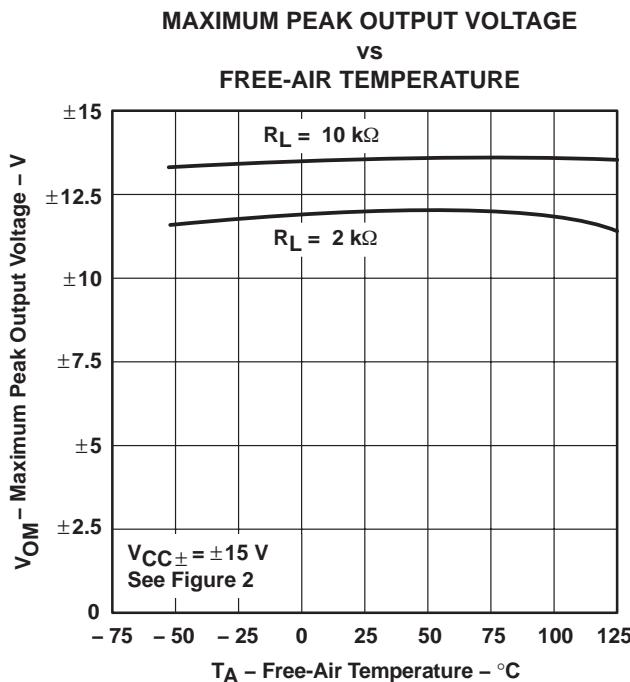


Figure 8

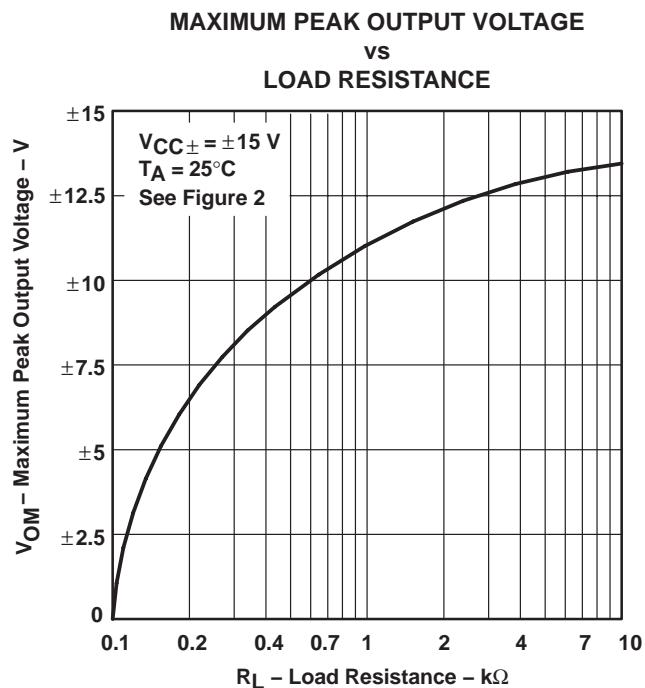


Figure 9

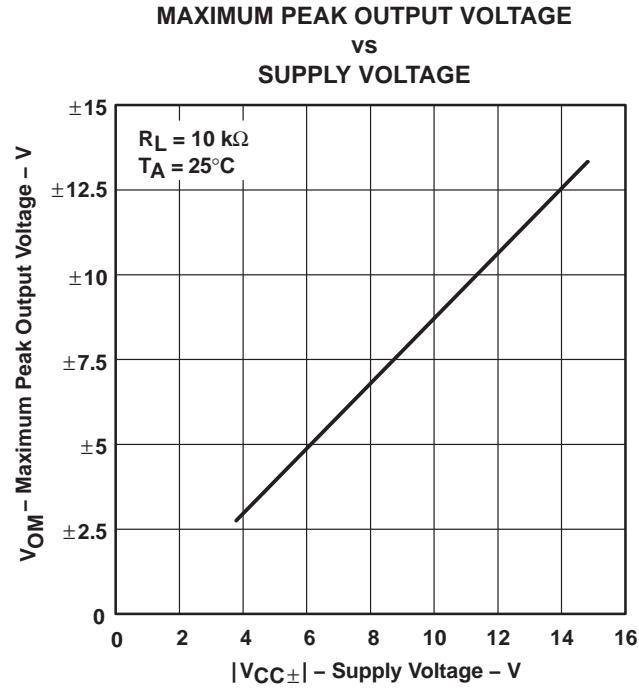


Figure 10

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS[†]

**LARGE-SIGNAL
DIFFERENTIAL VOLTAGE AMPLIFICATION
vs
FREE-AIR TEMPERATURE**

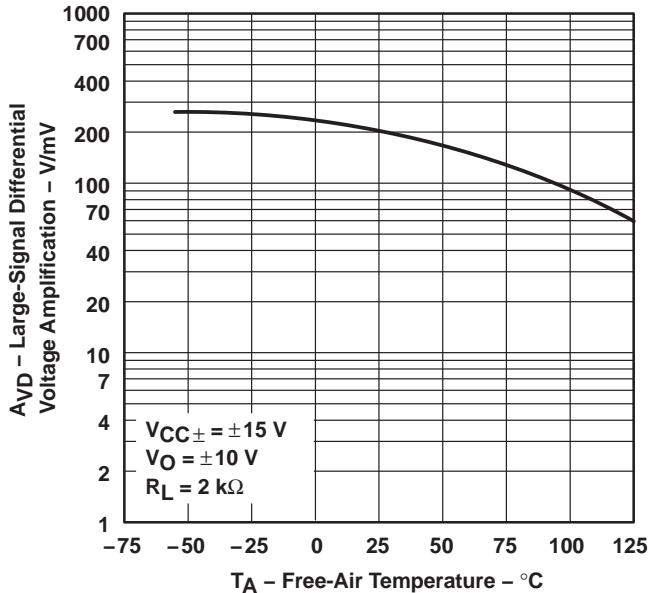


Figure 11

**LARGE-SIGNAL
DIFFERENTIAL VOLTAGE AMPLIFICATION
vs
FREQUENCY**

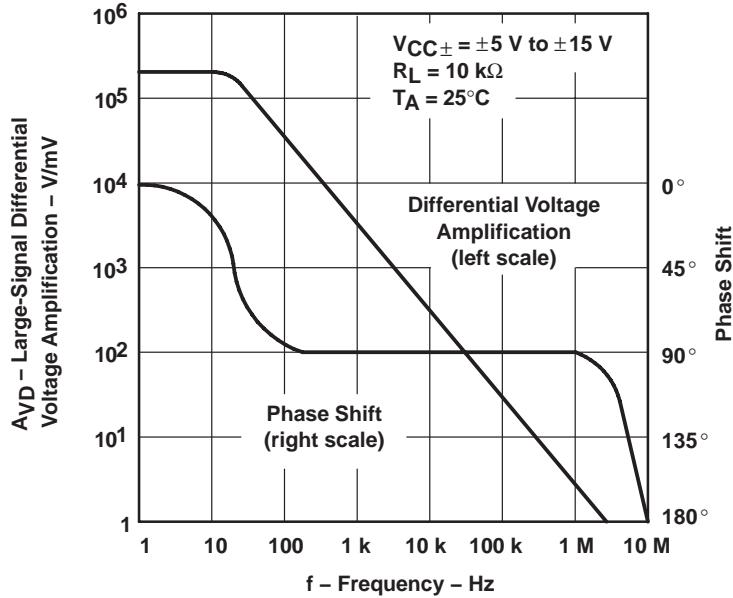


Figure 12

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
 TL084, TL084A, TL084B
 JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS081G – FEBRUARY 1977 – REVISED SEPTEMBER 2004

TYPICAL CHARACTERISTICS†

**DIFFERENTIAL VOLTAGE AMPLIFICATION
 VS
 FREQUENCY WITH FEED-FORWARD COMPENSATION**

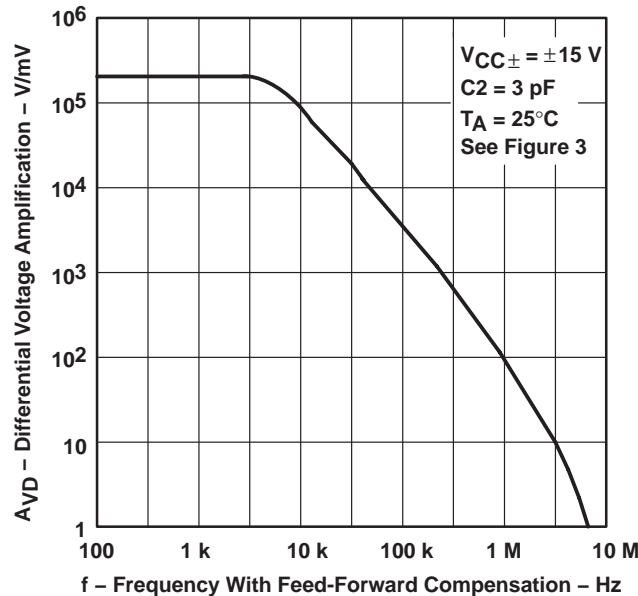


Figure 13

**TOTAL POWER DISSIPATION
 VS
 FREE-AIR TEMPERATURE**

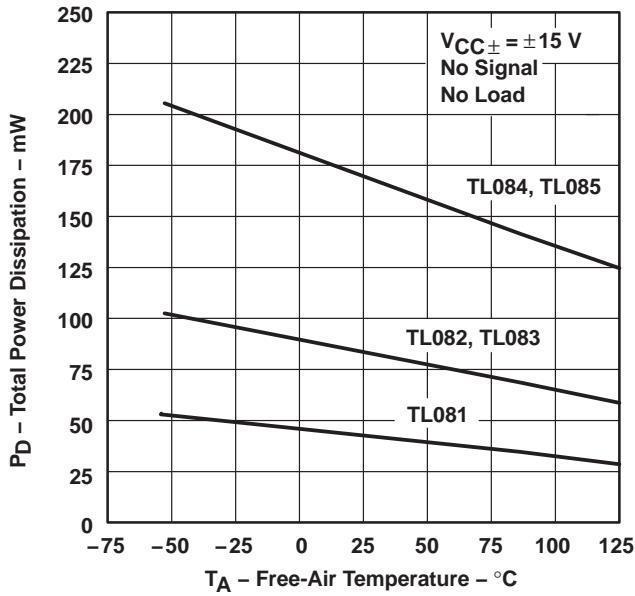


Figure 14

**SUPPLY CURRENT PER AMPLIFIER
 VS
 FREE-AIR TEMPERATURE**

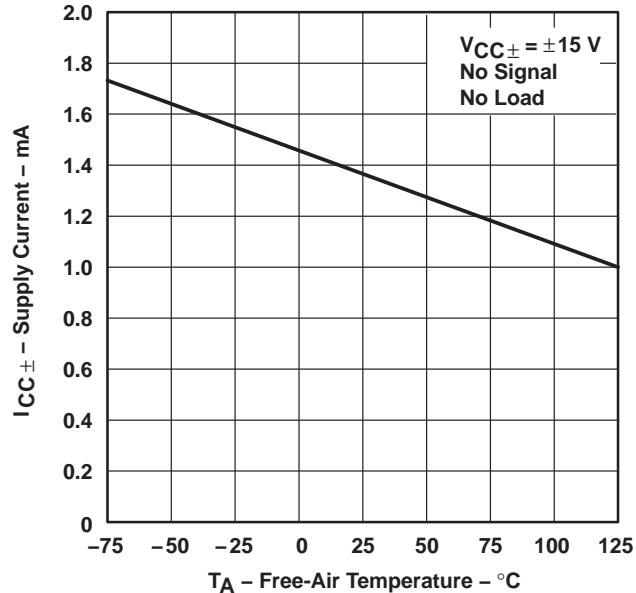


Figure 15

**SUPPLY CURRENT
 VS
 SUPPLY VOLTAGE**

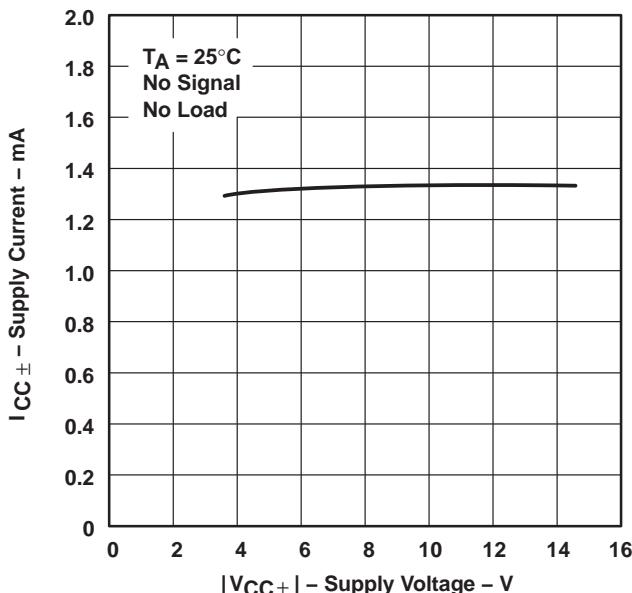


Figure 16

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†

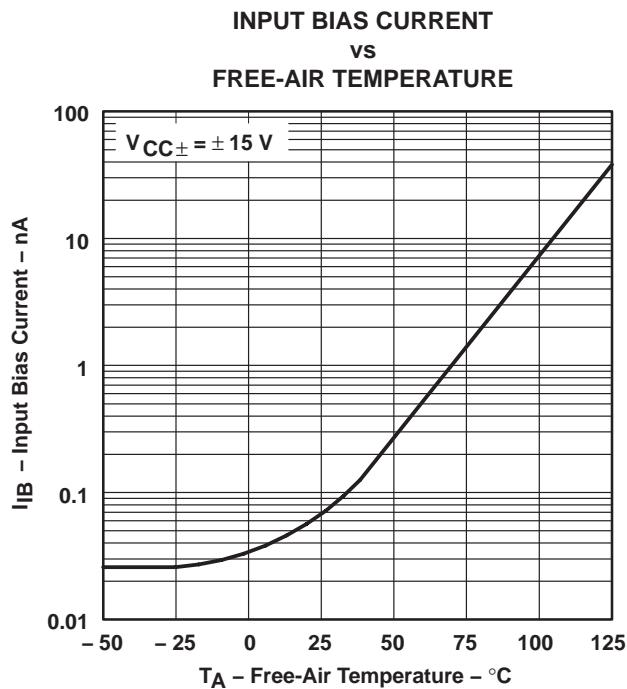


Figure 17

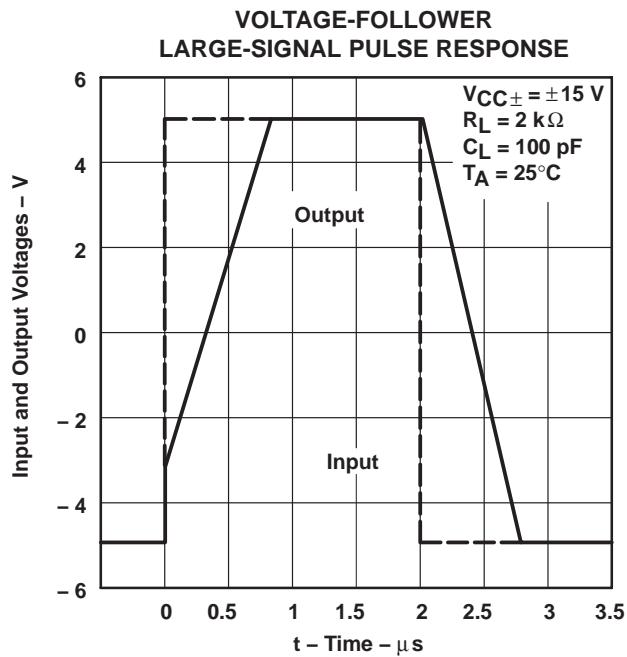


Figure 18

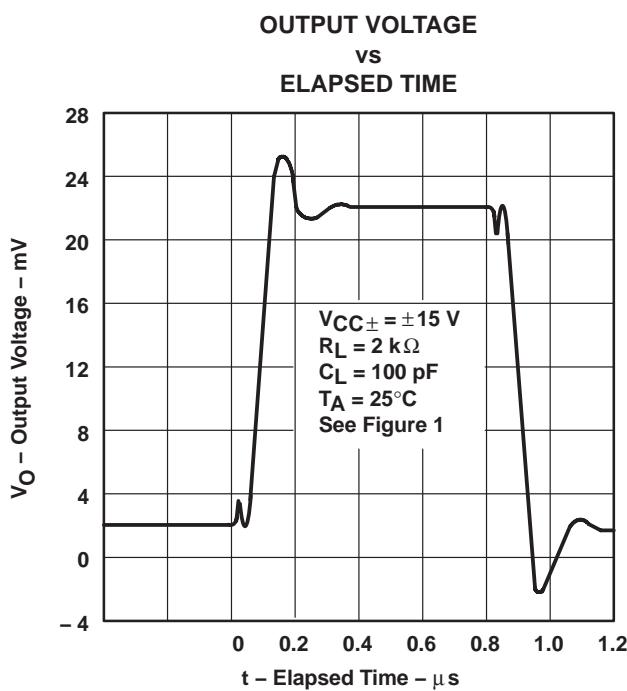


Figure 19

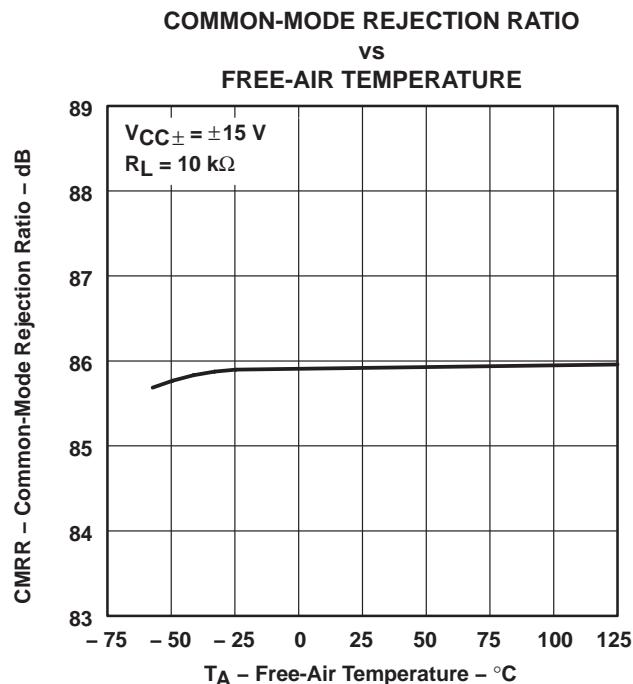


Figure 20

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B
JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS081G – FEBRUARY 1977 – REVISED SEPTEMBER 2004

TYPICAL CHARACTERISTICS†

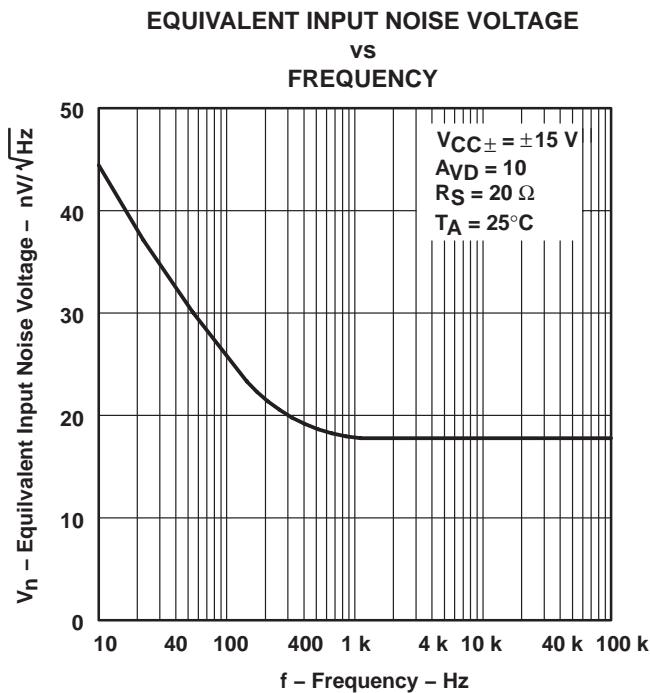


Figure 21

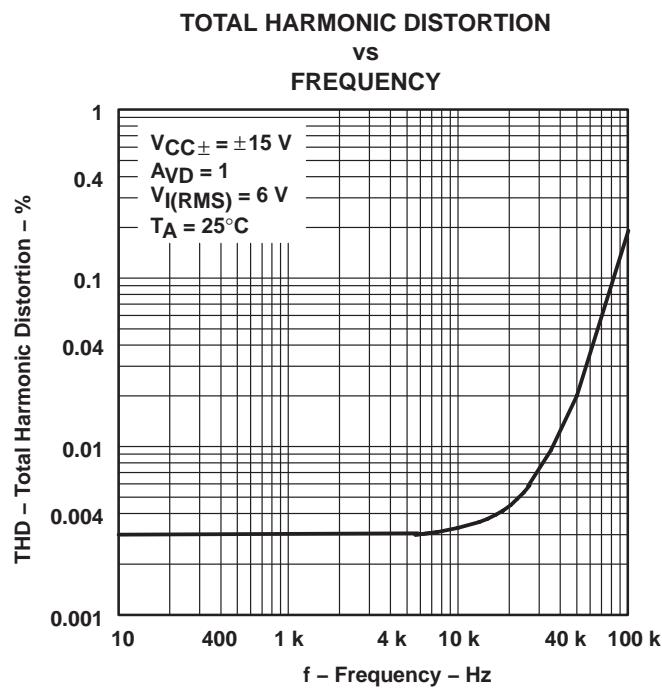


Figure 22

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

APPLICATION INFORMATION

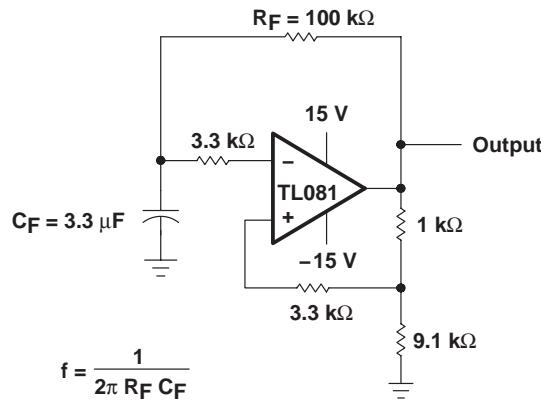


Figure 23

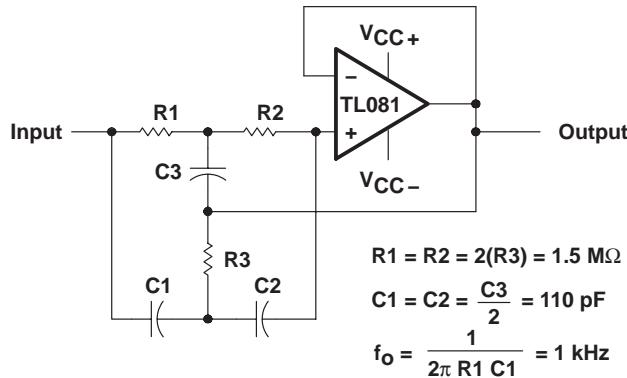


Figure 24

APPLICATION INFORMATION

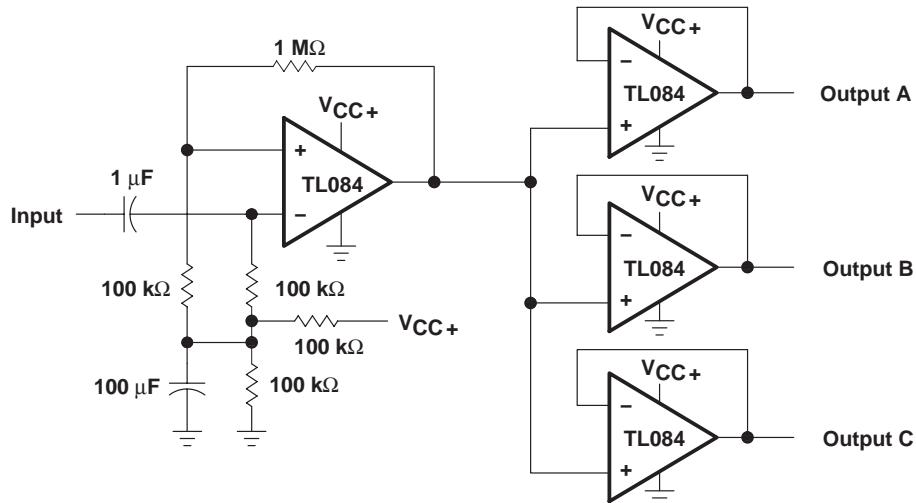
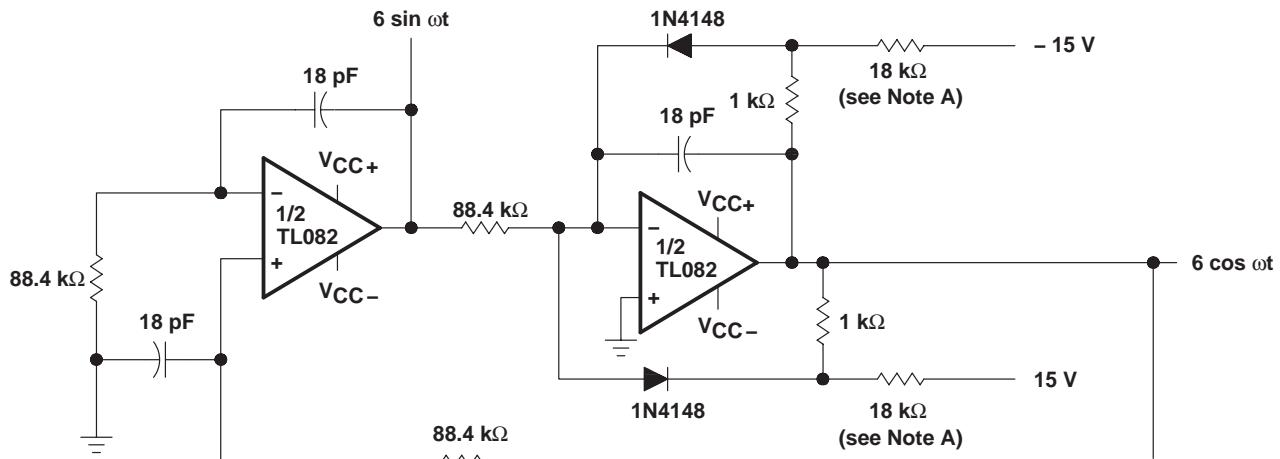


Figure 25. Audio-Distribution Amplifier



NOTE A: These resistor values may be adjusted for a symmetrical output.

Figure 26. 100-KHz Quadrature Oscillator

TL081, TL081A, TL081B, TL082, TL082A, TL082B

TL084, TL084A, TL084B

JFET-INPUT OPERATIONAL AMPLIFIERS

SLOS081G – FEBRUARY 1977 – REVISED SEPTEMBER 2004

APPLICATION INFORMATION

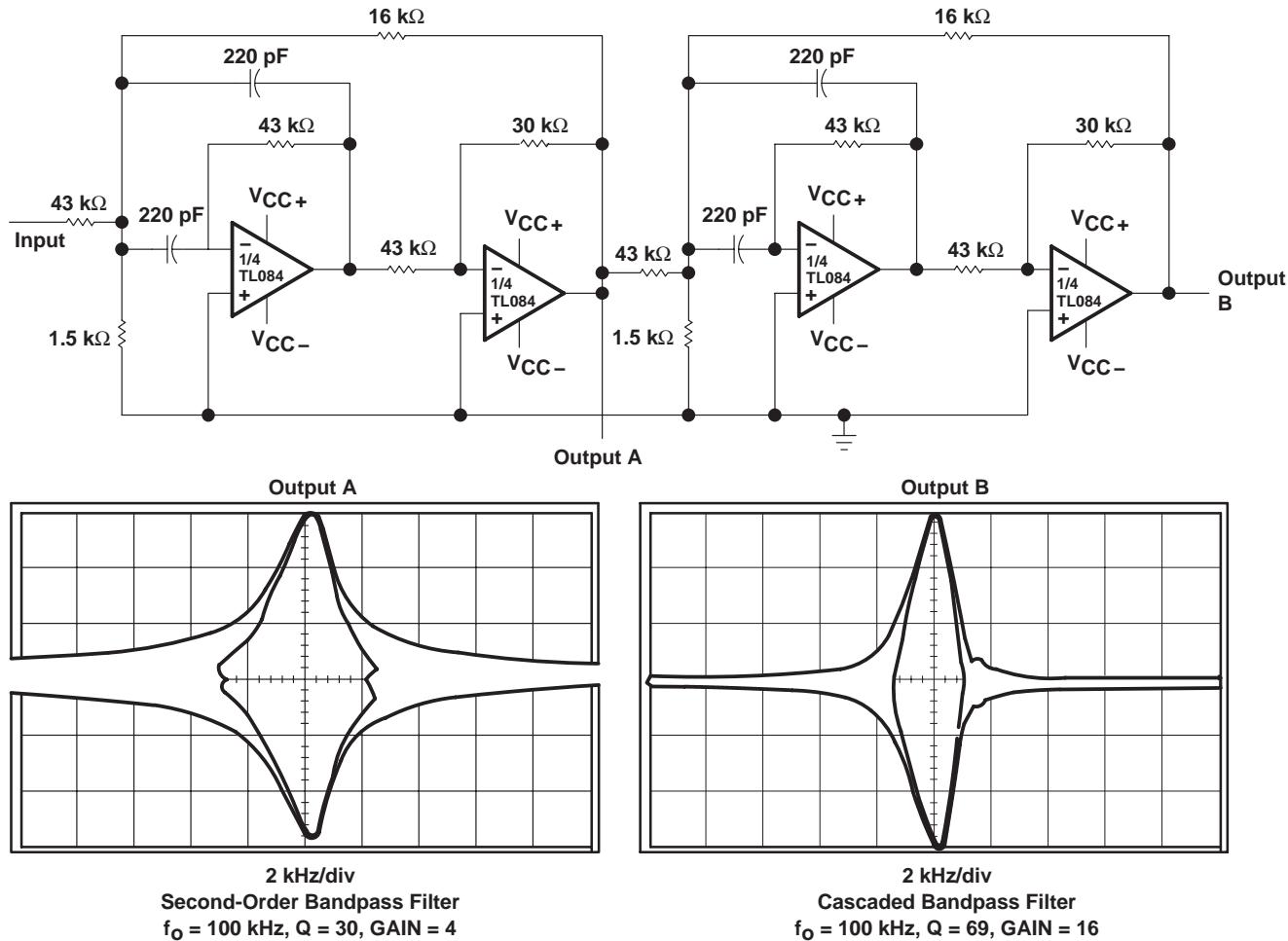


Figure 27. Positive-Feedback Bandpass Filter

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9851501Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9851501QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type
5962-9851503Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9851503QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
TL081ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACJG	OBsolete	CDIP	JG	8		TBD	Call TI	Call TI
TL081ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL081CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CPWLE	OBsolete	TSSOP	PW	8		TBD	Call TI	Call TI
TL081ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081MFKB	OBsolete	LCCC	FK	20		TBD	Call TI	Call TI
TL081MJG	OBsolete	CDIP	JG	8		TBD	Call TI	Call TI
TL081MJGB	OBsolete	CDIP	JG	8		TBD	Call TI	Call TI
TL082ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082ACPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
no Sb/Br)								
TL082BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CJG	OBsolete	CDIP	JG	8		TBD	Call TI	Call TI
TL082CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPWLE	OBsolete	TSSOP	PW	8		TBD	Call TI	Call TI
TL082CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL082ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL082IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082MFK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL082MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL082MJG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type
TL082MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type
TL084ACD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084ACNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084ACNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL084BCDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084BCNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
TL084CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084CNSLE	OBSOLETE	SO	NS	14		TBD	Call TI	Call TI
TL084CNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CPWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
TL084CPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL084IDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084IDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084IDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084IDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084IJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
TL084IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084INE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084MFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL084MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL084MJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
TL084MJB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
TL084QD	ACTIVE	SOIC	D	14	50	TBD	CU NIPDAU	Level-1-220C-UNLIM
TL084QDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084QDR	ACTIVE	SOIC	D	14	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
TL084QDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TL082, TL082M, TL084, TL084M :

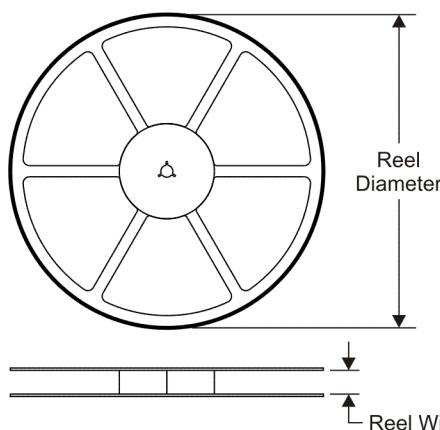
- Automotive: [TL082-Q1](#)

NOTE: Qualified Version Definitions:

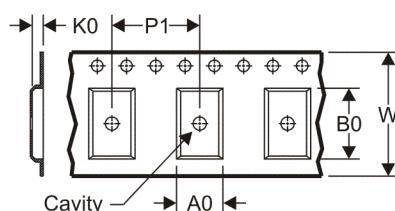
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

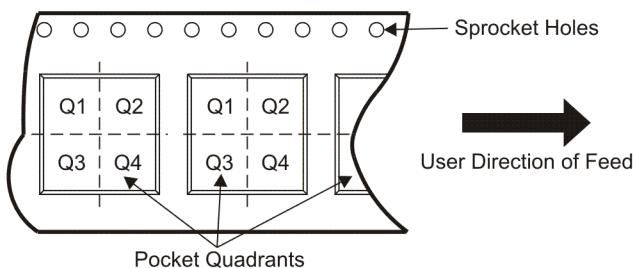


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

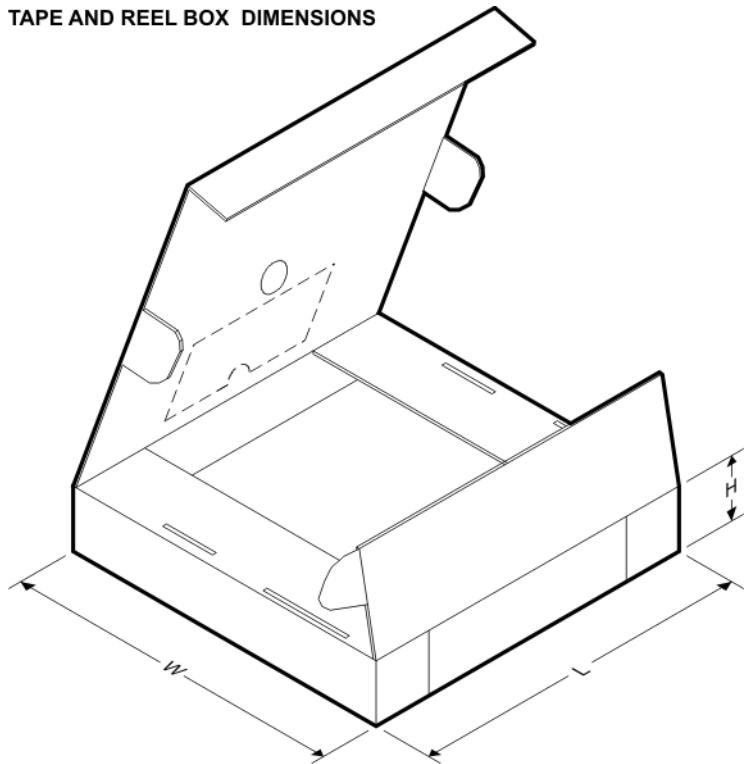
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL081ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL081BCDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL081CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL081CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL081IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082ACPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL082BCDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL082CPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL082IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL084ACDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL084ACDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL084ACNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TL084BCDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL084CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL084CNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TL084CPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TL084IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


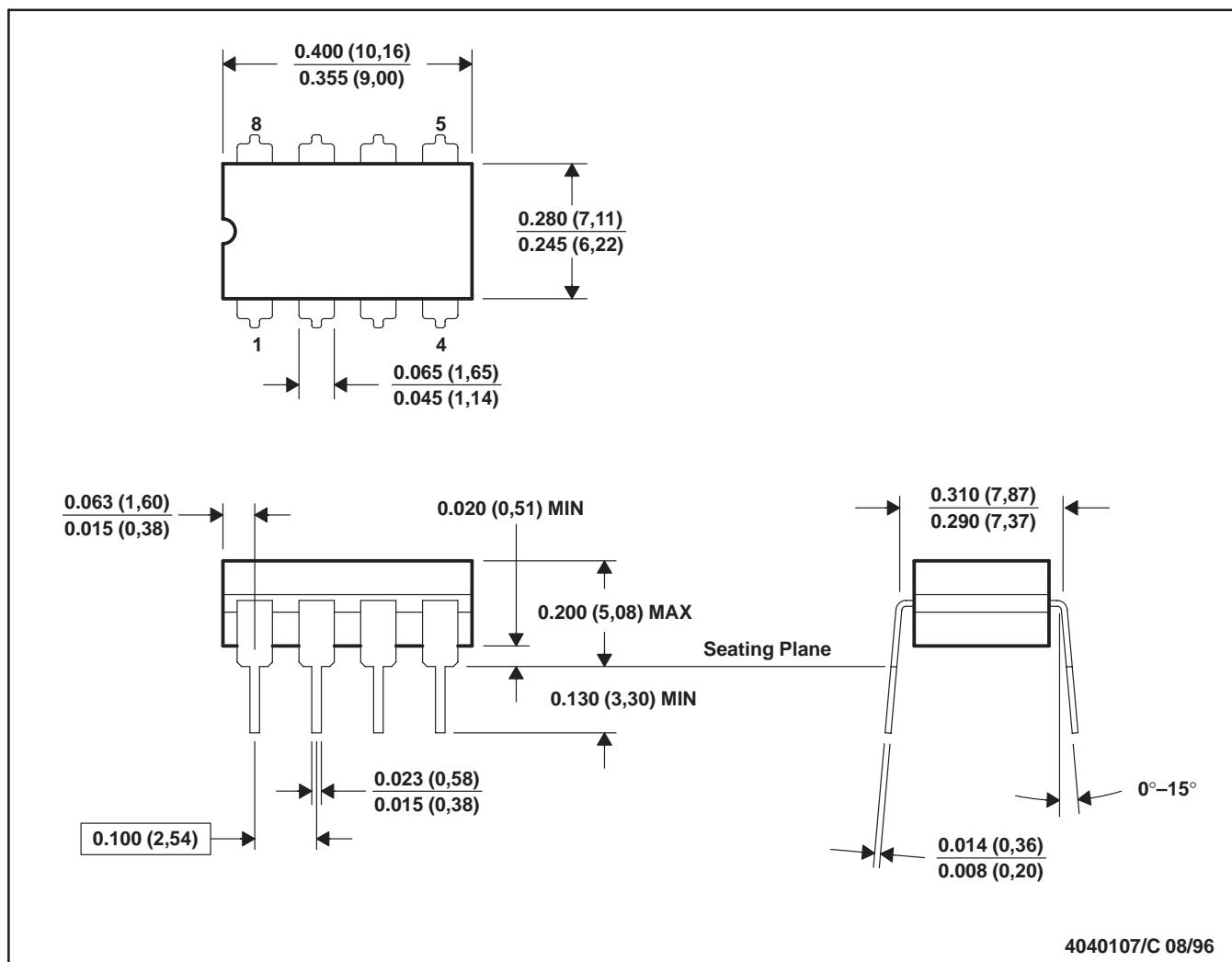
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL081ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TL081BCDR	SOIC	D	8	2500	340.5	338.1	20.6
TL081CDR	SOIC	D	8	2500	340.5	338.1	20.6
TL081CPSR	SO	PS	8	2000	346.0	346.0	33.0
TL081IDR	SOIC	D	8	2500	340.5	338.1	20.6
TL082ACDR	SOIC	D	8	2500	346.0	346.0	29.0
TL082ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TL082ACPSR	SO	PS	8	2000	346.0	346.0	33.0
TL082BCDR	SOIC	D	8	2500	340.5	338.1	20.6
TL082CDR	SOIC	D	8	2500	346.0	346.0	29.0
TL082CDR	SOIC	D	8	2500	340.5	338.1	20.6

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL082CPSR	SO	PS	8	2000	346.0	346.0	33.0
TL082CPWR	TSSOP	PW	8	2000	346.0	346.0	29.0
TL082IDR	SOIC	D	8	2500	340.5	338.1	20.6
TL082IDR	SOIC	D	8	2500	346.0	346.0	29.0
TL082IPWR	TSSOP	PW	8	2000	346.0	346.0	29.0
TL084ACDR	SOIC	D	14	2500	333.2	345.9	28.6
TL084ACDR	SOIC	D	14	2500	346.0	346.0	33.0
TL084ACNSR	SO	NS	14	2000	346.0	346.0	33.0
TL084BCDR	SOIC	D	14	2500	333.2	345.9	28.6
TL084CDR	SOIC	D	14	2500	333.2	345.9	28.6
TL084CNSR	SO	NS	14	2000	346.0	346.0	33.0
TL084CPWR	TSSOP	PW	14	2000	346.0	346.0	29.0
TL084IDR	SOIC	D	14	2500	333.2	345.9	28.6

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE

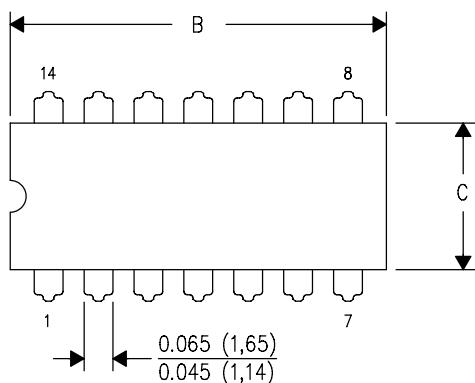


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification.
 - Falls within MIL STD 1835 GDIP1-T8

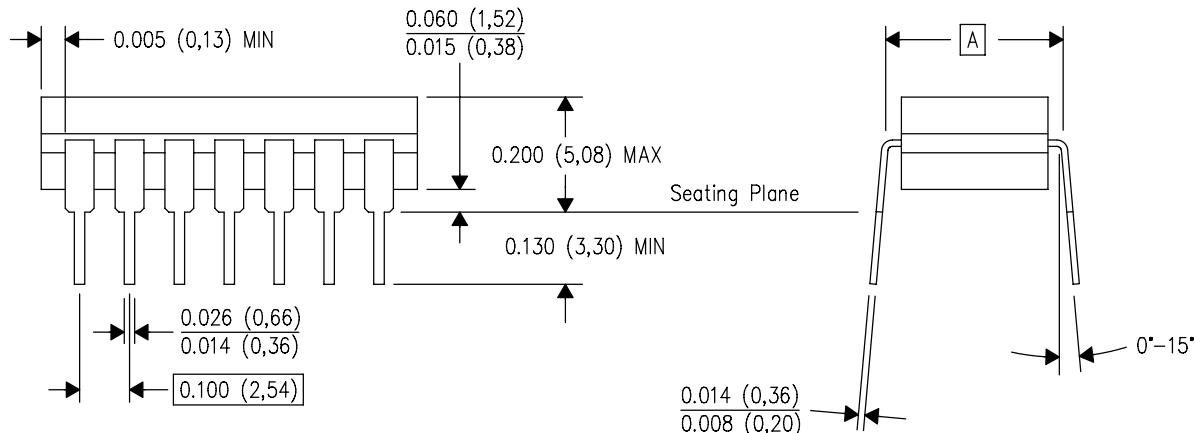
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS **\nDIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



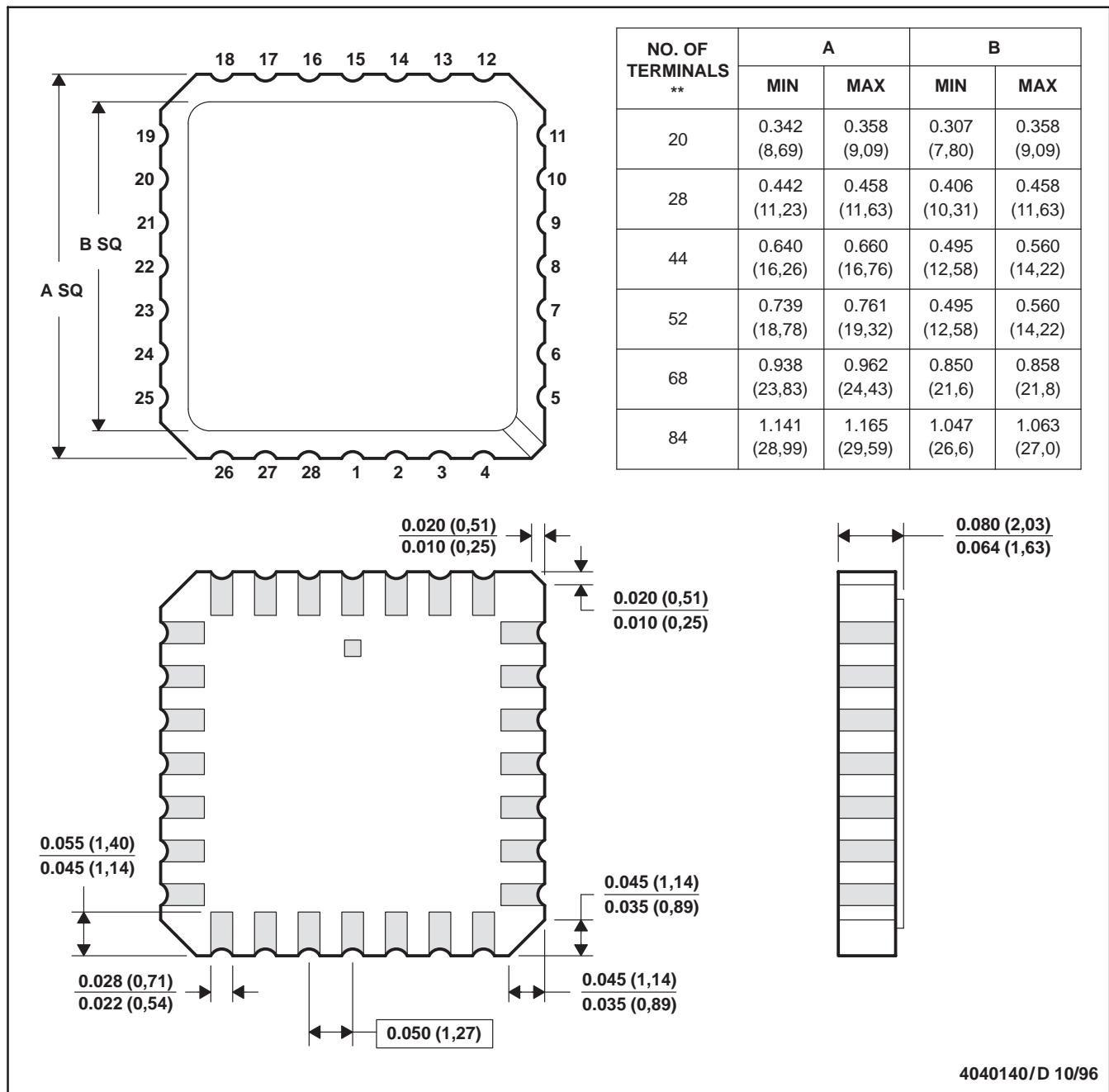
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. The terminals are gold plated.

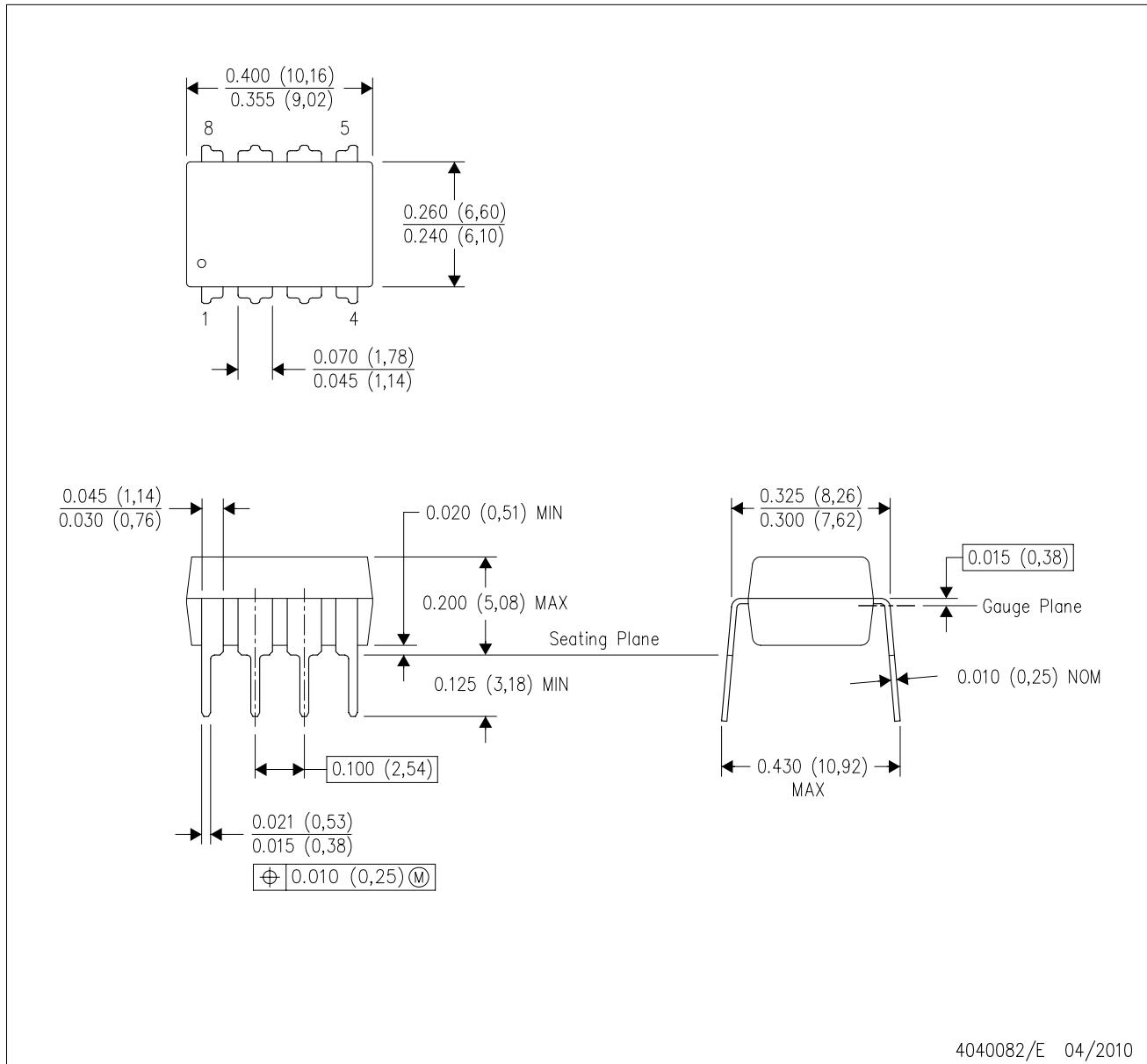
E. Falls within JEDEC MS-004

4040140/D 10/96

MECHANICAL DATA

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



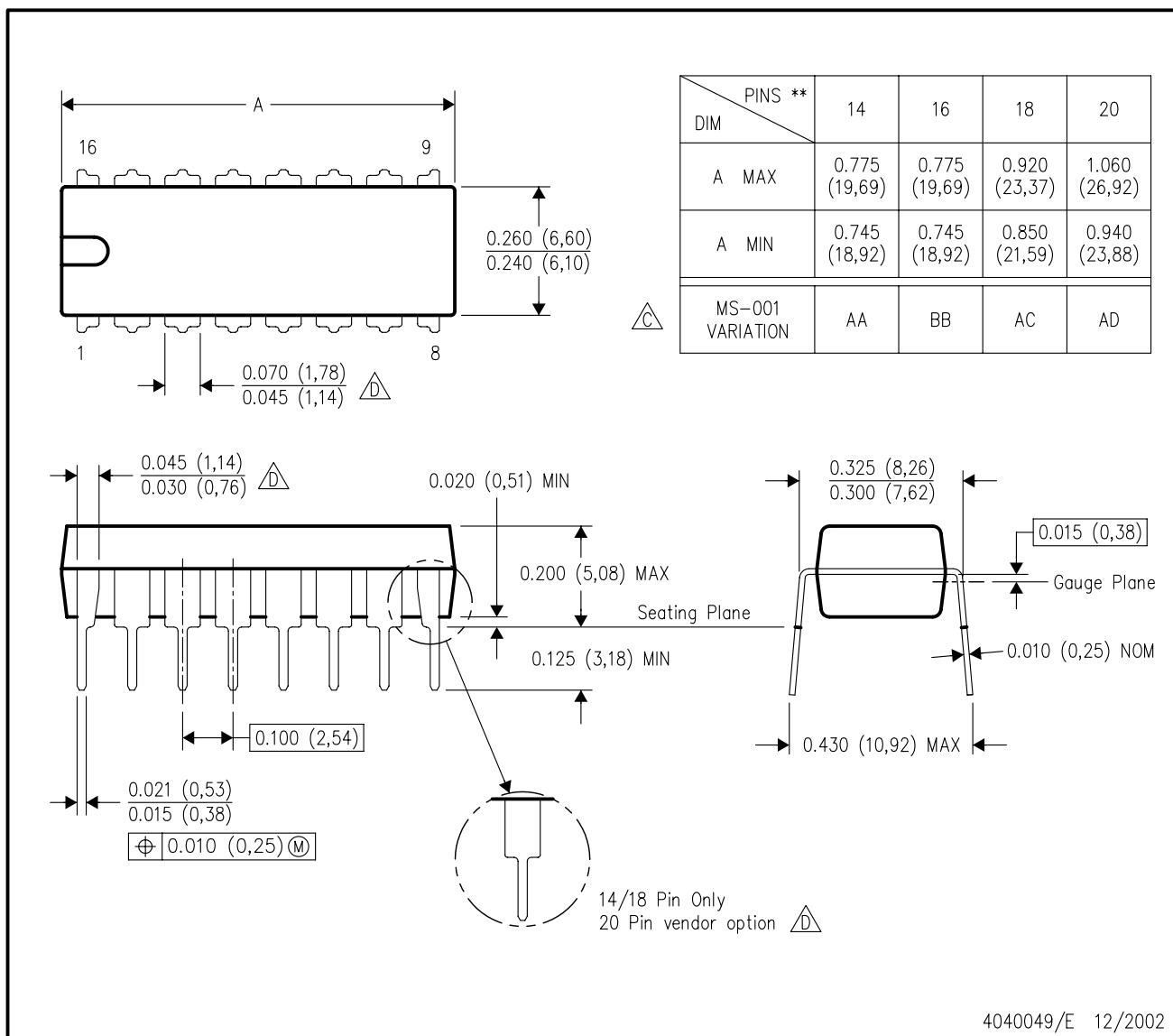
4040082/E 04/2010

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Falls within JEDEC MS-001 variation BA.

N (R-PDIP-T**)

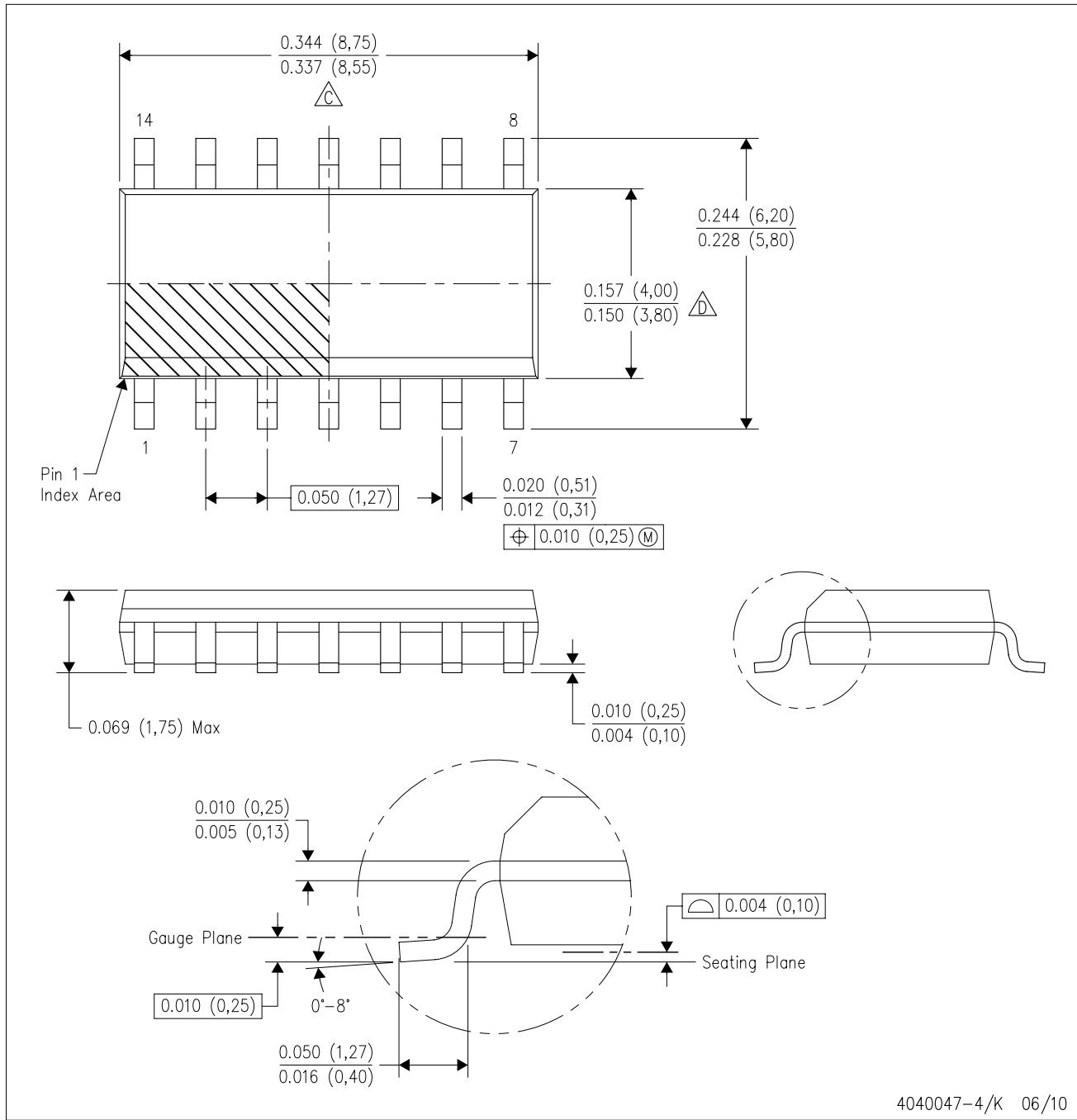
16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

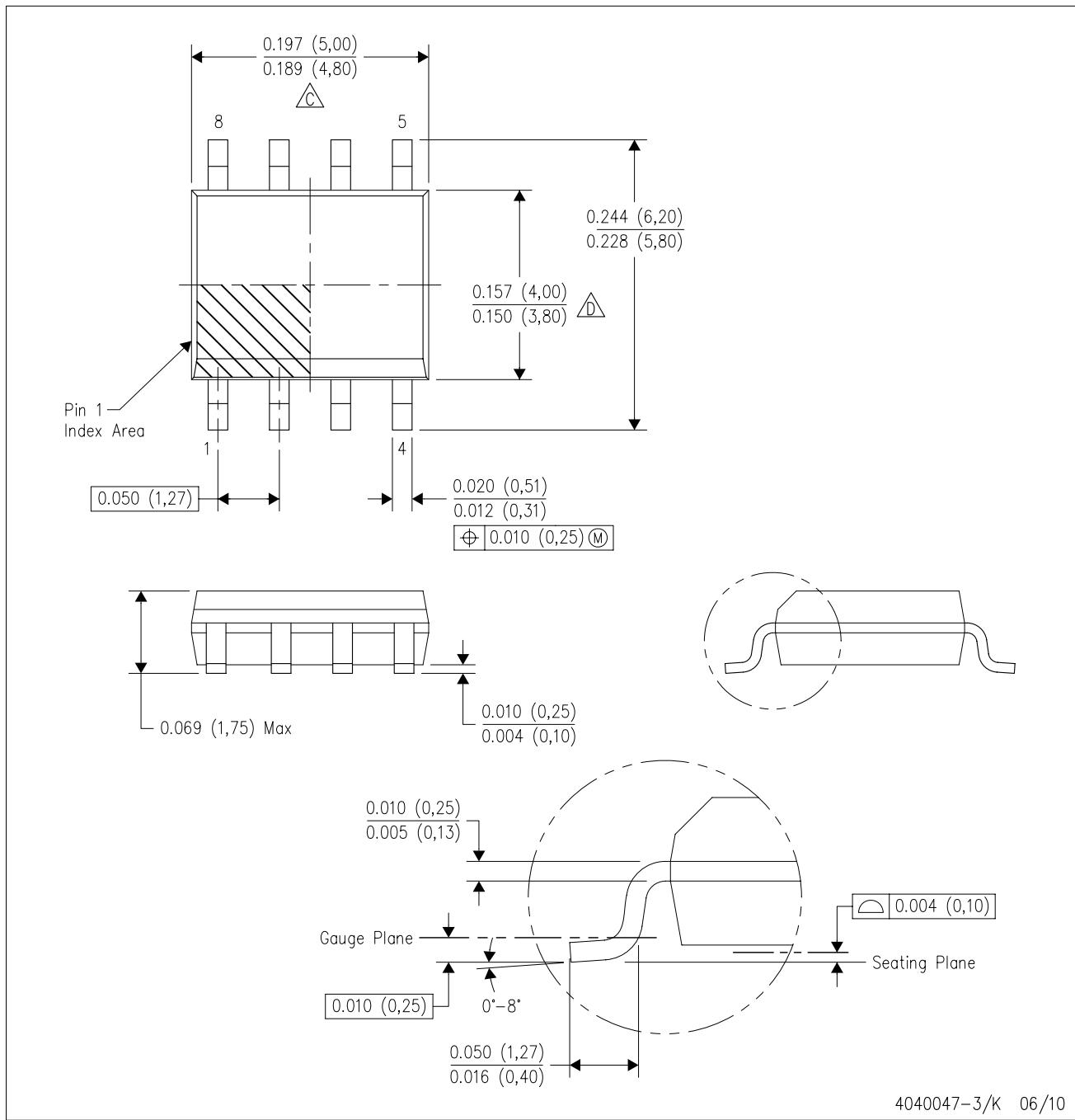
△C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

△D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

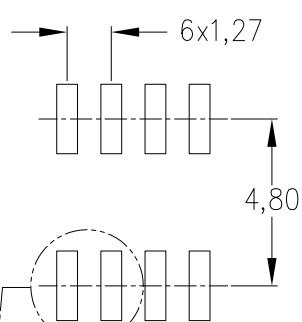
E. Reference JEDEC MS-012 variation AA.

LAND PATTERN DATA

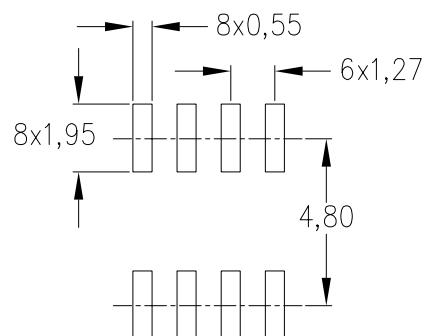
D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

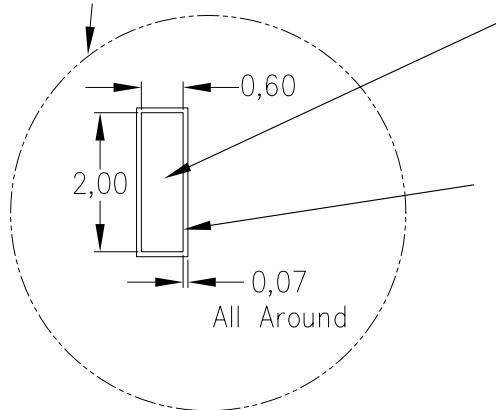
Example Board Layout
(Note C)



Stencil Openings
(Note D)



Example
Non Soldermask Defined Pad



Example
Pad Geometry
(See Note C)

Example
Solder Mask Opening
(See Note E)

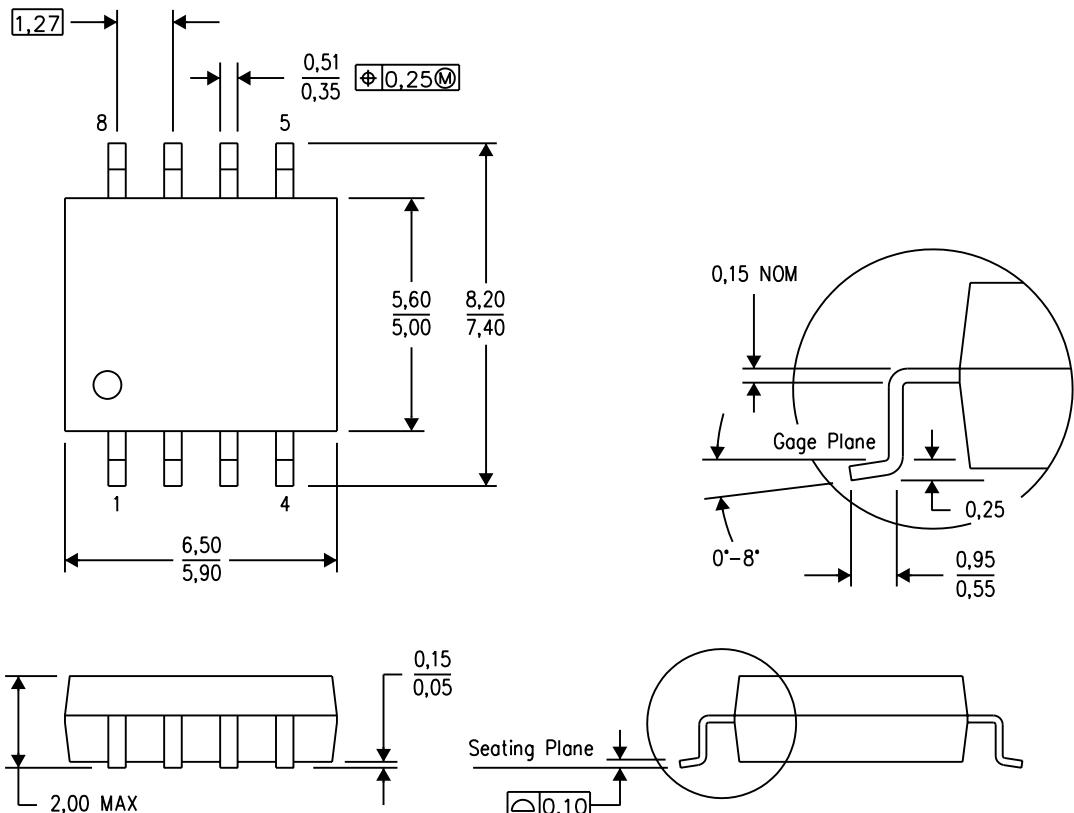
4211283-2/A 08/10

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



4040063/C 03/03

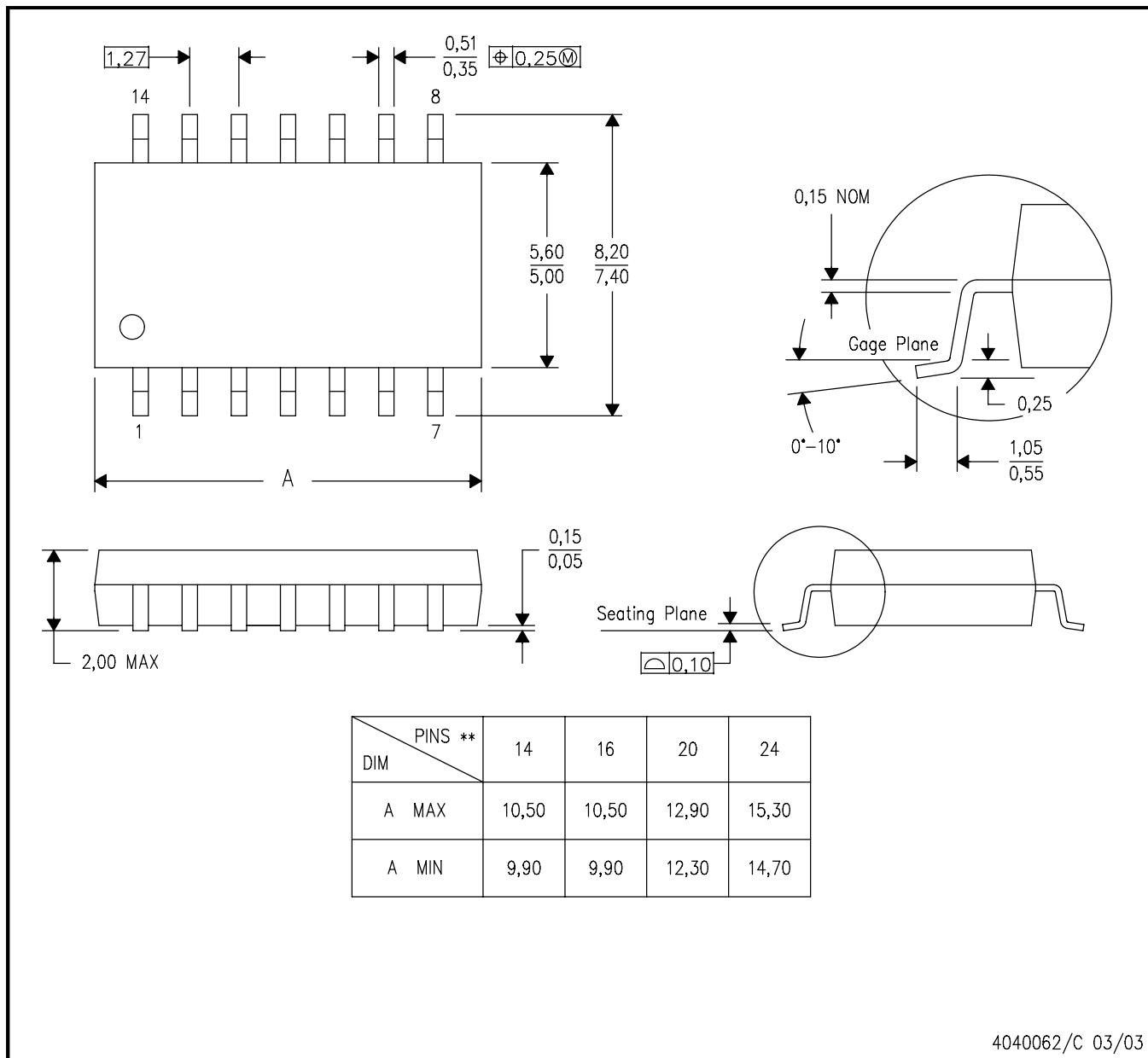
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

MECHANICAL DATA

NS (R-PDSO-G)**

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE

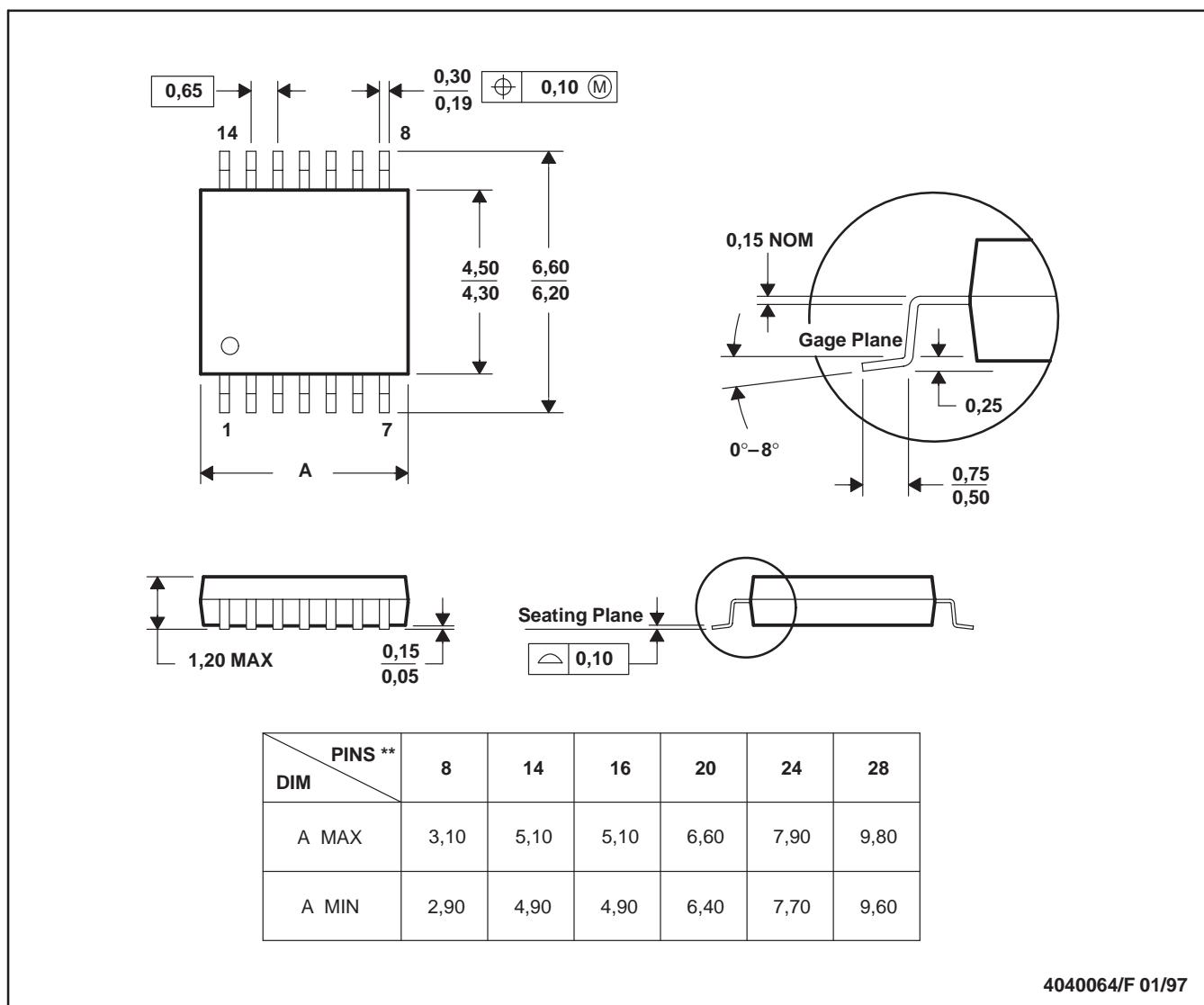


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G^{**})

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - Falls within JEDEC MO-153

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Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
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RF/IF and ZigBee® Solutions	www.ti.com/lprf	Video and Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless-apps